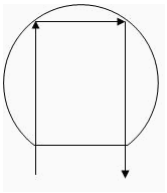
Part Number	Customer

Category		Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	150.00 +/- 0.50 mm	
	2.0	Primary Flat Orientation	{110}+/-0.5 degree	Wafer Vendor
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0	Overall Thickness	300.00 +/- 5.00 µm	ADE, 100%
	5.0	Total Thickness Variation (TTV)	<2.00µm	Guaranteed by Process
	6.0	Bow	<40.00µm	ADE to ASTM F534, 20%
	7.0	Warp	<40.00µm	ADE to ASTM F657, 20%
	8.0	Edge Chips	0	Bright Light, 100% (note 2)
HandleSilicon	9.0	Handle Growth Method	CZ	Wafer Vendor
	10.0	Handle Orientation	{100} +/- 0.5 degree	Wafer Vendor
	11.0	Handle Thickness	300.00 +/- 5.00 µm	ADE, 100%
	12.0	Handle Doping Type	P	Wafer Vendor
	13.0	Handle Dopant	Boron	Wafer Vendor
	14.0	Handle Resistivity	1-30 Ohmcm	Wafer Vendor
	15.0	Backside Finish	Polished with lasermarking - unique laser mark as per SEMI M12 (last 4 digits unique)	Wafer Vendor
	16.0	Surface Haze	0	Bright Light, 100% (note 2)
	17.0	Total scratch length	0	Bright Light, 100% (note 2)
	18.0	Total LPD Count	<30.00pces	@0.3um, Tencor 6220 particle counter

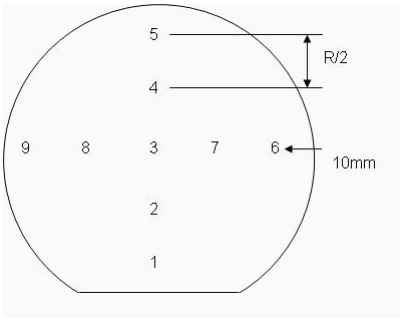
Part Number	Customer

Category	Parameter	Specification	Measurement Method
Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	
Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.		



2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information